

Groundbreaking of India's First Advanced 3D Semiconductor Packaging Unit in Odisha; Major Boost to AI, 5G and Defence Tech

Odisha Poised to Power PM Modi's Vision of Making India Self-Reliant in Semiconductor and Electronics Manufacturing: CM Mohan Charan Majhi

Odisha Emerges as Fast-Growing IT and Semiconductor Hub with Strong Electronics Manufacturing Push :Union Minister Ashwini Vaishnaw

Posted On: 19 APR 2026 5:02PM by PIB Bhubaneswar

In a defining moment for India's semiconductor ambitions and Odisha's emergence as a future-ready technology destination, the foundation stone for the country's first advanced 3D chip packaging unit was laid today at Info Valley, Bhubaneswar. The project marks a significant step towards strengthening India's domestic semiconductor ecosystem and advancing the vision of Atmanirbhar Bharat in high-end electronics manufacturing.





The foundation stone of the Heterogeneous Integration Packaging Solutions project, promoted by 3D Glass Solutions, was laid in the presence of Chief Minister Shri Mohan Charan Majhi and Union Minister for Railways, Electronics & Information Technology, and Information & Broadcasting Shri Ashwini Vaishnaw. With the launch of this project, Odisha is poised to become home to one of the world's most sophisticated chip packaging technologies.



Addressing the gathering, Chief Minister Shri Mohan Charan Majhi described the project as a historic milestone for Odisha and the nation. He said that for the first time in India, an advanced 3D Glass Solutions semiconductor project is being established, bringing immense pride to the state. He noted that global technology leaders such as Intel, Lockheed Martin, and Applied Materials are associated with cutting-edge packaging technologies, and their interest in Odisha reflects the state's growing industrial strength.

The Chief Minister flagged that the products manufactured in the state will support next-generation sectors such as Artificial Intelligence, high-performance computing, defence electronics, telecommunications, and advanced digital systems. "Odisha is ready to play a pivotal role in realising Prime Minister Shri Narendra Modi's vision of making India self-reliant in semiconductor and electronics manufacturing," he added.

Shri Majhi informed that the company is investing nearly ₹2,000 crore in the project and the facility is expected to produce 70,000 glass panels annually, along with 50 million assembled units and around 13,000 advanced 3DHI modules. He added that Odisha has emerged as the only state in the country where both India's first compound semiconductor fabrication unit and first 3D glass substrate packaging facility are being established.

He further said the growing semiconductor ecosystem in Odisha will open large-scale employment opportunities for engineering graduates, diploma holders, and ITI students, helping transform the state from a resource-based economy into a technology-led growth centre.



Addressing the gathering, Union Minister Shri Ashwini Vaishnaw congratulated the people of Odisha on the landmark initiative and appreciated the support extended by the State Government. He said, under the visionary leadership of Prime Minister Shri Narendra Modi, India's semiconductor sector is witnessing rapid growth, with Odisha emerging as an important contributor to this transformation.

Shri Vaishnaw said, Odisha, traditionally known for its strengths in minerals, metals and energy, is now steadily establishing itself in advanced sectors such as electronics, IT and semiconductors. Describing the project as one of the most advanced manufacturing initiatives of its kind, he said it would significantly strengthen India's semiconductor value chain.

Highlighting the country's progress in electronics manufacturing, Shri Vaishnaw said production in the sector has grown six-fold over the past 12 years. "India has now become the world's second-largest mobile phone manufacturer and emerged as the leading exporter of mobile phones in 2025", he added.

He further informed that two semiconductor projects have already been approved for Odisha under the India Semiconductor Mission, while three more electronics and semiconductor-related proposals are in the pipeline. "Discussions are also underway with major global companies, including Intel for future investments in the state," he mentioned.

Speaking on railway infrastructure, Shri Vaishnaw said, projects worth over ₹90,000 crore are currently under execution in Odisha, reflecting an unprecedented expansion of rail connectivity. He added that the state has received a record railway budget allocation of ₹10,928 crore, while 59 stations are being redeveloped under the Amrit Bharat Station Scheme. He further said that all 30 districts of Odisha are being brought under rail connectivity through planned interventions, alongside key projects such as the proposed four-line coastal rail corridor from Balasore to Berhampur. Shri Vaishnaw emphasized that these transformative initiatives will strengthen regional connectivity, support economic growth, and integrate Odisha more closely with national freight and passenger networks.

Reiterating the Government's vision, he affirmed that railway infrastructure across Odisha will continue to be upgraded with a focus on speed, safety, and passenger comfort, ensuring balanced and inclusive development across all regions of the state.

State Minister for Electronics & IT, Dr. Mukesh Mahaling, said Odisha is fast emerging as a semiconductor hub, with two approved projects under the India Semiconductor Mission, including the advanced 3D Glass unit inaugurated today. He said the State Government's IT, AI, GCC and Semiconductor Policies 2025 will drive innovation and attract investments.

Emphasising skill development, he said stipend support for engineering students is being provided to build an industry-ready workforce. He added that initiatives like the Blackswan Summit 2026 and growing AI investments will create jobs and strengthen Odisha's leadership in future technologies.

The project is being implemented by 3D Glass Solutions Inc. (3DGS), USA, through its wholly owned Indian subsidiary Heterogeneous Integration Packaging Solutions Pvt. Ltd. (HIPSPL) at Info Valley in Khordha district. It is a greenfield, vertically integrated advanced packaging and embedded glass substrate ATMP facility.

The total investment in the project is ₹1,943.53 crore, including approved Central fiscal support of ₹799 crore and additional State support of approximately ₹399.5 crore.

The facility will cater to high-growth sectors such as data centres, Artificial Intelligence, machine learning, 5G/6G communications, automotive radar, defence electronics, aerospace applications, and photonics. Commercial production is expected to begin by August 2028, while full-scale volume production is targeted by August 2030.

The event was attended by several distinguished dignitaries, including Shri S. Krishnan Secretary, Ministry of Electronics & IT, Government of India, Smt. Anu Garg Chief Secretary of Odisha, Shri Hemant Sharma Additional Chief Secretary, Industries Department, Shri Vishal Kumar Dev Additional Chief Secretary, Electronics & IT Department and Shri Babu Mandava Chairman & CEO of 3D Glass Solutions.

Subhalaxmi/Swadhin/Manoj/Manish

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